SCOPE OF CLAIMED INVENTION:

1. A method for manufacturing a semiconductor device, the method comprising the steps of:

mounting a first semiconductor chip on a substrate;

mounting a base member outside the first semiconductor chip on the substrate; and

mounting a second semiconductor chip that is larger than the first semiconductor chip on the first semiconductor chip, in a manner that the second semiconductor chip is supported by the base member.

2. A method for manufacturing a semiconductor device, the method comprising the steps of:

mounting a first semiconductor chip on a substrate,

mounting a second semiconductor chip that is larger than the first semiconductor chip on the first semiconductor chip; and

providing a filler layer in a manner to support the second semiconductor chip.

3. A method of manufacturing a semiconductor device comprising:

disposing a first semiconductor chip on a substrate;

disposing a base member on said substrate;

disposing a second semiconductor chip on said first semiconductor chip; and

wire-bonding said second semiconductor chip to said interposer substrate,

wherein said second semiconductor chip is larger than said first semiconductor chip such that edges of said second semiconductor chip extending beyond said first semiconductor chip are supported by said base member.

4. A method of manufacturing a semiconductor chip according to Claim 3, wherein said base member is disposed in a frame shape surrounding said first semiconductor chip.

5. A method of manufacturing a semiconductor chip according to Claim 3, wherein said base member is disposed as a column-like member.